



Final Product Change Notification

201912030F01

Issue Date: 12-Jan-2020

Effective Date: 11-Apr-2020

Dear *Emma Tempest*,

Here's your personalized quality information concerning products Premier Farnell PLC purchased from NXP.

For detailed information we invite you to [view this notification online](#)

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QUALITY

Management Summary

The LPC54(S)018Jx products are changing to revision 1C for improved bondability.

Change Category

☒ Wafer Fab Process	☐ Assembly Process	☐ Product Marking	☐ Test Location	☐ Design
☐ Wafer Fab Materials	☐ Assembly Materials	☐ Mechanical Specification	☐ Test Process	☐ Errata
☐ Wafer Fab Location	☐ Assembly Location	☐ Packing/Shipping/Labeling	☐ Test Equipment	☐ Electrical spec./Test coverage
☐ Firmware	☐ Other			

LPC54(S)018JxM Revision
Change to 1C for Wirebond
Improvement

Description of Change

The LPC54(S)018JxM products have been upgraded to include an additional metal layer on the serial flash die for improved for wire bonding.

The product revision changes from "1B" to "1C".

The LPC microcontroller die and package does not change.

Reason for Change

To improve the wire bonding performance for high volume manufacturing.

Identification of Affected Products

Top side marking

The last character of the last line in the top side marking changes from "B" to "C".

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment 10-Apr-2020

Anticipated Impact on Form, Fit, Function, Reliability or Quality

The last character of the last line in the top side marking changes from "B" to "C".

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Affected products and sales history information: see attached file

Self qualification: [view online](#)



Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 11-Feb-2020.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Tim Camenzind

Position Quality Manager

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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